

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3183135

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	KIJUN KIM	11/24/2014
	JONGHYUN PARK	11/24/2014
	HANBYUL SEO	11/25/2014
RECEIVING PARTY DATA		
Name:	LG ELECTRONICS INC.	
Street Address:	20 YEOUIDO-DONG, YEONGDEUNGPO-GU	
City:	SEOUL	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	150-721	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	14414864	
CORRESPONDENCE DATA		
Fax Number:	(213)623-2211	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	213-623-2221	
Email:	patent@lhlaw.com	
Correspondent Name:	LEE, HONG, DEGERMAN, KANG & WAIMEY	
Address Line 1:	660 S. FIGUEROA STREET	
Address Line 2:	SUITE 2300	
Address Line 4:	LOS ANGELES, CALIFORNIA 90017	
ATTORNEY DOCKET NUMBER:	2101-5985	
NAME OF SUBMITTER:	HARRY S. LEE	
SIGNATURE:	/Harry S. Lee/	
DATE SIGNED:	01/14/2015	
Total Attachments: 1		
source=9_2101-5985_Assignment#page1.tif		

ASSIGNMENT

(1-8) Insert Name(s) of
Inventor(s)

(1) Kijun KIM (5)
(2) Jonghyun PARK (6)
(3) Hanbyul SEO (7)
(4) (8)

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(9) Insert name of Assignee

(9) LG Electronics Inc.

(10) Insert state of Incorporation
of Assignee

(10) Republic of Korea

(11) Insert address of Assignee

(11) 20 Yeouido-dong, Yeongdeungpo-gu, Seoul, 150-721, Republic of Korea

(hereinafter designated as the Assignee) the entire worldwide right, title and interest in the invention known as

(12) Insert identification of
Invention, such as Title,
Case Number or Foreign
Application Number

(12) **METHOD AND DEVICE FOR REPORTING CHANNEL STATE
INFORMATION IN WIRELESS COMMUNICATION SYSTEM**

for which the undersigned has (have) executed an application for patent in the United States of America and all patent applications in foreign countries corresponding thereto or based thereon.

1) The undersigned agree(s) to execute all papers necessary in connection with any original, reissue, divisional and continuing United States and foreign applications for the above-identified invention and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed any agreement in conflict herewith.

The undersigned hereby appoints **the Attorneys associated with Customer No. 35884** the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: 2014/11/24 Signature of Inventor (1) [Signature]
Date: 2014/11/24 Signature of Inventor (2) [Signature]
Date: 2014.11.25 Signature of Inventor (3) [Signature]

PATENT